

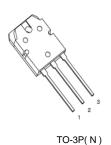
K1304-VB Datasheet N-Channel 100-V (D-S) 175 °C MOSFET

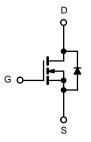
| PRODUCT SUMMARY | | | |
|---------------------|-------------------------------------------|--------------------|--|
| V _{DS} (V) | $R_{DS(on)}(\Omega)$ | I _D (A) | |
| 100 | $0.0085 \text{ at V}_{GS} = 10 \text{ V}$ | 100 | |
| | 0.010 at V _{GS} = 6 V | 85 | |

FEATURES

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted | | | | | |
|--------------------------------------------------------------------------------|----------------------------------------------|-----------------------------------|------------------|------|--|
| Parameter | | Symbol | Limit | Unit | |
| Drain-Source Voltage | | V _{DS} | 100 | V | |
| Gate-Source Voltage | | V _{GS} | ± 20 | V | |
| Continuous Drain Current (T _J = 150 °C) | T _C = 25 °C | I _D | 100 | | |
| | T _C = 125 °C | | 75 ^a | A | |
| Pulsed Drain Current | | I _{DM} | 300 | | |
| Avalanche Current | L = 0.1 mH | I _{AS} | 75 | | |
| Single Pulse Avalanche Energy ^b | L = 0.1 IIII1 | E _{AS} | 280 | mJ | |
| Maximum Power Dissipation ^b | $T_C = 25$ °C (TO-220AB and TO-263) | P _D | 250 ^c | W | |
| | T _A = 25 °C (TO-263) ^d | | 3.75 |] ** | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 175 | °C | |

| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------|---------------------------------|-------------------|-------|------|
| Parameter | | Symbol | Limit | Unit |
| Junction-to-Ambient | PCB Mount (TO-263) ^d | R _{thJA} | 40 | °C/W |
| Junction-to-Ambient | Free Air (TO-220AB) | TthJA | 62.5 | |
| Junction-to-Case | | R _{thJC} | 0.6 | |

Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|-----------------------------------------------|-----------------------------|-------------------------------------------------------------------------|------|--------|-------|------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 100 | | | V |
| Gate-Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 1 | | 3 | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 100 V, V _{GS} = 0 V | | | 1 | μА |
| | | V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C | | | 50 | |
| | | V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C | | | 250 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 120 | | | Α |
| Drain-Source On-State Resistance ^a | | V _{GS} = 10 V, I _D = 30 A | | 0.0085 | | Ω |
| | D. | V _{GS} = 4.5 V, I _D = 20 A | | 0.010 | | |
| | R _{DS(on)} | V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C | | 0.017 | | |
| | | V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C | | 0.022 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 30 A | 25 | | | S |
| Dynamic ^b | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz | | 6550 | | pF |
| Output Capacitance | C _{oss} | | | 665 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 265 | | |
| Total Gate Charge ^c | Q_g | | | 105 | 160 | nC |
| Gate-Source Charge ^c | Q _{gs} | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$ | | 17 | | |
| Gate-Drain Charge ^c | Q_{gd} | 1 | | 23 | | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 12 | 25 | ns |
| Rise Time ^c | t _r | $V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$ | | 90 | 135 | |
| Turn-Off DelayTime ^c | t _{d(off)} | $I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$ | | 55 | 85 | |
| Fall Time ^c | t _f | | | 130 | 195 | |
| Source-Drain Diode Ratings and Char | racteristics T _C | = 25 °C ^b | | | | |
| Continuous Current | Is | | | | 85 | Α |
| Pulsed Current | I _{SM} | | | | 240 | |
| Forward Voltage ^a | V _{SD} | I _F = 85 A, V _{GS} = 0 V | | 1.0 | 1.5 | V |
| Reverse Recovery Time | t _{rr} | | | 85 | 140 | ns |
| Peak Reverse Recovery Current | I _{RM(REC)} | I _F = 50 A, dI/dt = 100 A/μs | | 4.5 | 7 | Α |
| Reverse Recovery Charge | Q _{rr} | 1 | | 0.17 | 0.35 | μС |

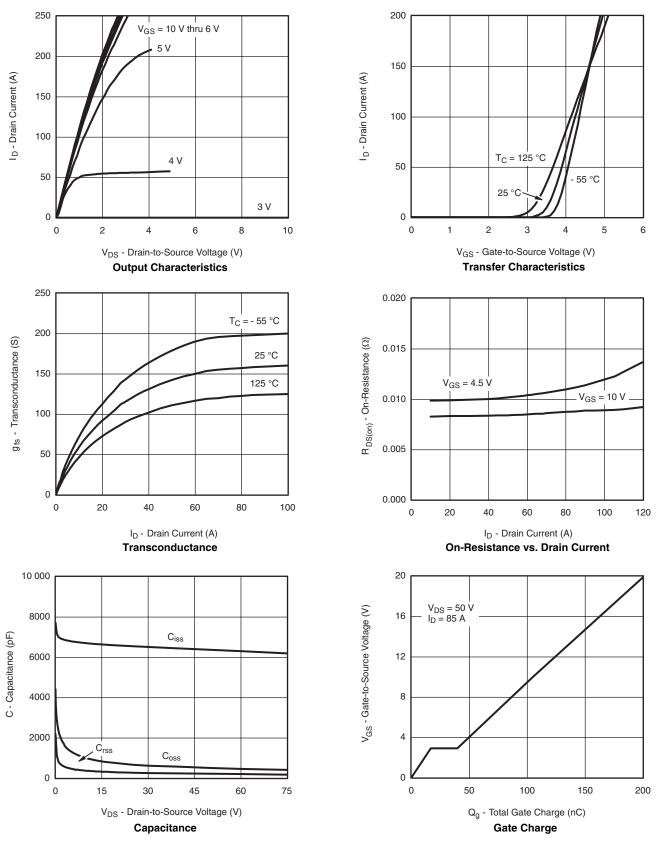
Notes:

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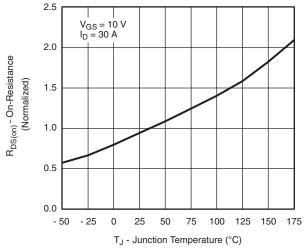


TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted

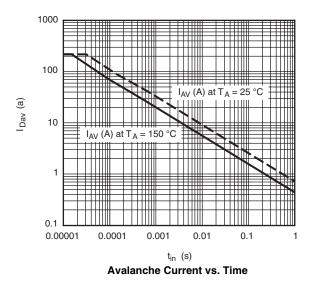




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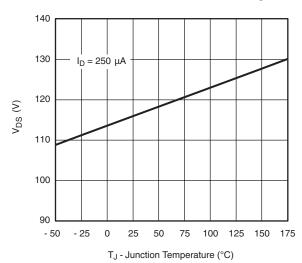


On-Resistance vs. Junction Temperature



T_J = 150 °C T_J = 25 °C T_J

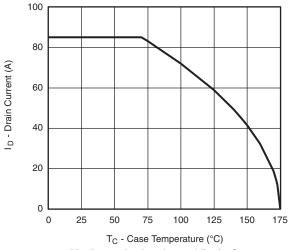
Source-Drain Diode Forward Voltage



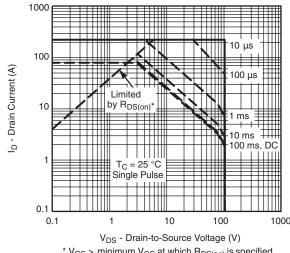
T_J - Drain-Source Breakdown vs. Junction-Temperature



THERMAL RATINGS

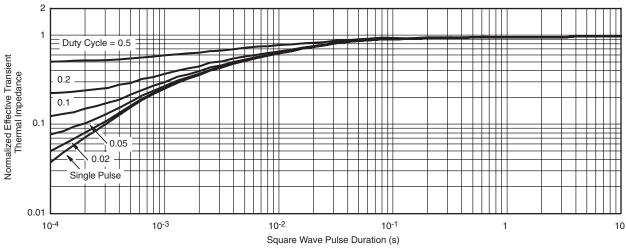


Maximum Avalanche and Drain Current vs. Case Temperature



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

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